

65V N-Channel MOSFETs

General Description

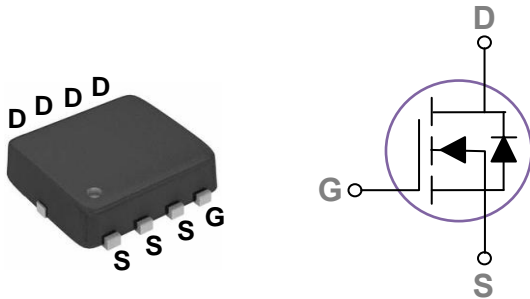
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV_{DSS}	$R_{DS(ON)Max.}$	I_D
65V	16m Ω	38A

Features

- 65V, 38A, $R_{DS(ON)Max.} = 16m\Omega @ V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

PPAK3×3 Pin Configuration



Applications

- Motor Drive
- Power Tools
- LED Lighting

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	65V	V
V_{GS}	Gate-Source Voltage	+20/-20V	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	38	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	24	A
I_{DM}	Drain Current – Pulsed ¹	152	A
E_{AS}	Single Pulse Avalanche Energy ²	42	mJ
I_{AS}	Single Pulse Avalanche Current ²	29	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	63	W
T_{STG}	Storage Temperature Range	-50 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-50 to 150	$^\circ\text{C}$

Note 1: Exceed these limits to damage to the device.

Note 2: Exposure to absolute maximum rating conditions may affect device reliability.

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	65			V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=60V, V_{GS}=0V, T_J=25^\circ\text{C}$			1	μA
		$V_{DS}=48V, V_{GS}=0V, T_J=85^\circ\text{C}$			10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=20V, V_{DS}=0V$			100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=12A$		12.6	16	m Ω
		$V_{GS}=4.5V, I_D=5A$		25	33	m Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.8	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient			-5		mV/°C
gfs	Forward Transconductance	$V_{DS}=5V, I_D=13A$		38		S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{2,3}	$V_{DS}=30V, V_{GS}=10V, I_D=15A$		14		nC
Q_{gs}	Gate-Source Charge ^{2,3}			3.5		
Q_{gd}	Gate-Drain Charge ^{2,3}			4.5		
$T_{d(on)}$	Turn-On Delay Time ^{2,3}	$V_{DD}=30V, V_{GS}=10V, R_G=6\Omega$ $I_D=1A$		7.2		ns
T_r	Rise Time ^{2,3}			9		
$T_{d(off)}$	Turn-Off Delay Time ^{2,3}			17		
T_f	Fall Time ^{2,3}			6		
C_{iss}	Input Capacitance	$V_{DS}=20V, V_{GS}=0V, F=1\text{MHz}$		810		pF
C_{oss}	Output Capacitance			175		
C_{riss}	Reverse Transfer Capacitance			35		
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$		2.2		Ω

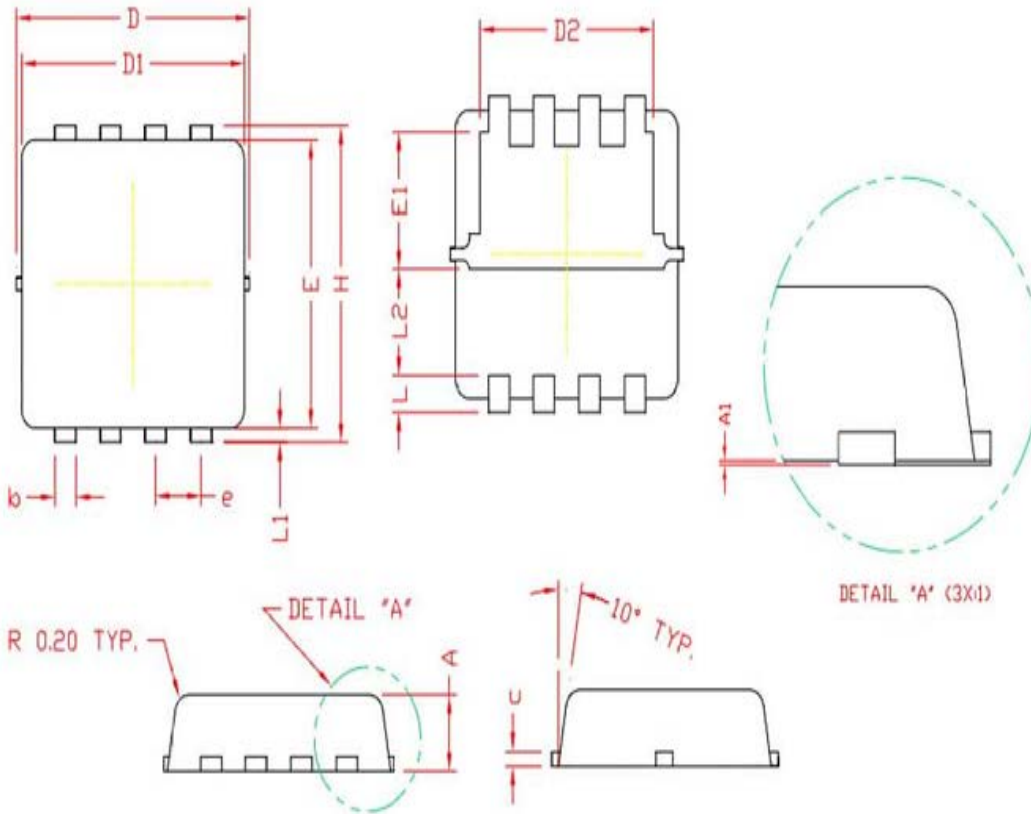
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_{GS}=V_D=0V$, Force Current			38	A
I_{SM}	Pulsed Source Current				76	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$			1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=29A, R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.
3. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

PPAK3×3 PACKAGE INFORMATION



COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.70	0.80	0.90
A1	0.00	0.03	0.05
b	0.24	0.30	0.35
c	0.10	0.15	0.20
D	3.25	3.32	3.40
D1	3.05	3.15	3.25
D2	2.40	2.50	2.60
E	3.00	3.10	3.20
E1	1.35	1.45	1.55
e	0.65 BSC.		
H	3.20	3.30	3.40
L	0.30	0.40	0.50
L1	0.10	0.15	0.20
L2	1.13 REF.		